



Application

LGA 1366/1356 (Socket B/B2) M3

Test result:

	65W	95W
Flow (CFM)	Rca (°C/W)	Rca (°C/W)
8	0.392	0.392
10	0.353	0.346
12	0.324	0.317
15	0.294	0.287
16	0.287	0.279
20	0.255	0.248
25	0.232	0.224
30	0.216	0.207

Safety



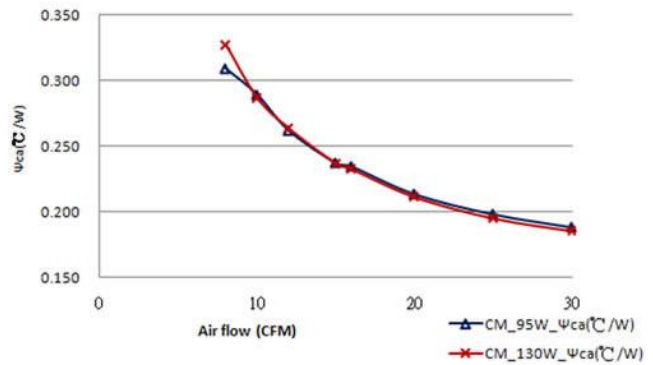
Thermal and Mechanical Spec

Thermal performance for 65W/95W CPU

HSK Assembly Weight: 256 g

CPU Loading: 65 lbf

Performance Curve



Component Specifications

Application System 1U+ Form Factor Passive Solution

Material Aluminum Fin + Aluminum Base + Heat pipe Diameter 6 × 3

Dimension 88.9L × 88.9W × 26.75H mm

Fin Thick=0.3mm, Pitch=2.3mm, 68 fin (Solder Free)

Thermal interface Material Shin Etsu 7783 (36 × 36 mm)

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.